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|--------------------------|--|-------------------------------------|---------------------|
| PCN Number: | 20190820001 | PCN Date: | Aug. 26, 2019 |
| Title: | Datasheet for MSP430FR2633, MSP430FR2632, MSP430FR2533, MSP430FR2532 □ | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Data Sheet |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Material |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Materials |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Process |

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



MSP430FR2633, MSP430FR2632, MSP430FR2533, MSP430FR2532

SLAS942D – NOVEMBER 2015 – REVISED AUGUST 2019

Changes from revision C to revision D

| Changes from August 29, 2018 to August 19, 2019 | Page |
|---|--------------------|
| • Updated Section 1.1, Features | 1 |
| • Added "Target development board" information in Section 1.1, Features | 2 |
| • Changed " $f_{CONVER} = 2$ MHz" to " $f_{CONVER} = 4$ MHz" in the note that begins "CapTIvate technology works in LPM3 with 64 mutual-capacitance buttons" on Section 5.7, Low-Power Mode (LPM3 and LPM4) Supply Currents (Into V_{CC}) Excluding External Current | 22 |
| • Changed from R_1 to R_{1MUX} in Table 5-20, ADC, Power Supply and Input Range Conditions | 40 |
| • Added R_{1MISC} TYP value 34k Ω in Table 5-20, ADC, Power Supply and Input Range Conditions | 40 |
| • Added formula for R_1 calculation in Table 5-21, ADC, 10-Bit Timing Parameters | 40 |
| • Removed the description of " $\pm 3^\circ\text{C}$ " in table note that starts "The device descriptor structure ..." of Table 5-22, ADC, 10-Bit Linearity Parameters | 41 |
| • Moved C_{REG} and $C_{ELECTRODE}$ from Section 5.3, Recommended Operating Conditions to Table 5-23, CapTIvate Electrical Characteristics | 42 |
| • Added test condition for $C_{ELECTRODE}$ in Table 5-23, CapTIvate Electrical Characteristics | 42 |
| • Changed the symbol and description of the DC_{CAPCLK} parameter in Table 5-23, CapTIvate Electrical Characteristics | 42 |
| • Moved the SNR parameter to Table 5-24, CapTIvate Signal-to-Noise Ratio Characteristics | 42 |
| • Corrected bitfield from IRDSEL to IRDSSEL in Section 6.10.8, Timers (Timer0_A3, Timer1_A3, Timer2_A2 and Timer3_A2) , in the description that starts "The interconnection of Timer0_A3 and ..." | 56 |
| • Corrected the ADCINCHx column heading in Table 6-15, ADC Channel Connections | 58 |
| • Corrected the ADCSHSx column heading in Table 6-16, ADC Trigger Signal Connections | 58 |
| • Added P1SELC information in Table 6-32, Port P1, P2 Registers (Base Address: 0200h) | 71 |
| • Added P2SELC information in Table 6-32, Port P1, P2 Registers (Base Address: 0200h) | 71 |
| • Added P3SELC information in Table 6-33, Port P3 Registers (Base Address: 0220h) | 71 |
| • Updated Section 7.2.2, CapTIvate Peripheral | 81 |

The datasheet number will be changing.

| Device Family | Change From: | Change To: |
|--|--------------|------------|
| MSP430FR2633, MSP430FR2632, MSP430FR2533, MSP430FR2532 □ | SLAS942C | SLAS942D |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSP430FR2633>

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|---|-------------------|-------------------|-------------------|
| Reason for Change: | | | |
| To accurately reflect device characteristics. | | | |
| Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): | | | |
| No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. | | | |
| Changes to product identification resulting from this PCN: | | | |
| None. | | | |
| Product Affected: | | | |
| MSP430FR2532IRGER | MSP430FR2533IRHBR | MSP430FR2632IYQWR | MSP430FR2633IRHBR |
| MSP430FR2532IRGET | MSP430FR2533IRHBT | MSP430FR2632IYQWT | MSP430FR2633IRHBT |
| MSP430FR2533IDA | MSP430FR2632IRGER | MSP430FR2633IDA | MSP430FR2633IYQWR |
| MSP430FR2533IDAR | MSP430FR2632IRGET | MSP430FR2633IDAR | MSP430FR2633IYQWT |

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